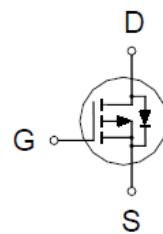


P2003EEAA

P-Channel Logic Level Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-30V	20mΩ @ $V_{GS} = -10V$	-25A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ²	$T_C = 25^\circ C$	I_D	-25	A
	$T_C = 100^\circ C$		-16	
	$T_A = 25^\circ C$		-8	
	$T_A = 70^\circ C$		-6.3	
Pulsed Drain Current ¹		I_{DM}	-80	
Avalanche Current		I_{AS}	-29	
Avalanche Energy	$L = 0.1mH$	E_{AS}	42	mJ
Power Dissipation	$T_C = 25^\circ C$	P_D	20.8	W
	$T_C = 100^\circ C$		8.3	
	$T_A = 25^\circ C$		2	
	$T_A = 70^\circ C$		1.2	
Operating Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

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THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ³	Steady-State	R _{θJA}		62	
Junction-to-Ambient	Steady-State	R _{θJC}		6	°C / W

¹Pulse width limited by maximum junction temperature.

²Package limitation current is 30A.

³The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C. The value in any given application depends on the user's specific board design.

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			-100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -24V, V _{GS} = 0V			-1	μA
		V _{DS} = -20V, V _{GS} = 0V, T _J = 125 °C			-10	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = -5V, V _{GS} = -10V	-80			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = -4.5V, I _D = -7A		23	35	mΩ
		V _{GS} = -10V, I _D = -9A		15	20	
Forward Transconductance ¹	g _{fs}	V _{DS} = -5V, I _D = -9A		23		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz		1300		pF
Output Capacitance	C _{oss}			212		
Reverse Transfer Capacitance	C _{rss}			200		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		2.8		Ω
Total Gate Charge ²	Q _g (V _{GS} =-10V)	V _{DS} = 0.5V _{(BR)DSS} , I _D = -9A		29.4		nC
	Q _g (V _{GS} =-4.5V)			15.6		
Gate-Source Charge ²	Q _{gs}			3.8		
Gate-Drain Charge ²	Q _{gd}			7.8		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} = -15V, I _D ≈ -9A, V _{GS} = -10V, R _{GS} = 6Ω		20		nS
Rise Time ²	t _r			12		
Turn-Off Delay Time ²	t _{d(off)}			55		
Fall Time ²	t _f			36		

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SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				-25	A
Forward Voltage ¹	V_{SD}	$I_F = -9\text{A}, V_{GS} = 0\text{V}$			-1	V
Reverse Recovery Time	t_{rr}	$I_F = -9\text{A}, dI_F/dt = 100\text{A} / \mu\text{s}$		14.3		nS
Reverse Recovery Charge	Q_{rr}			4.2		nC

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

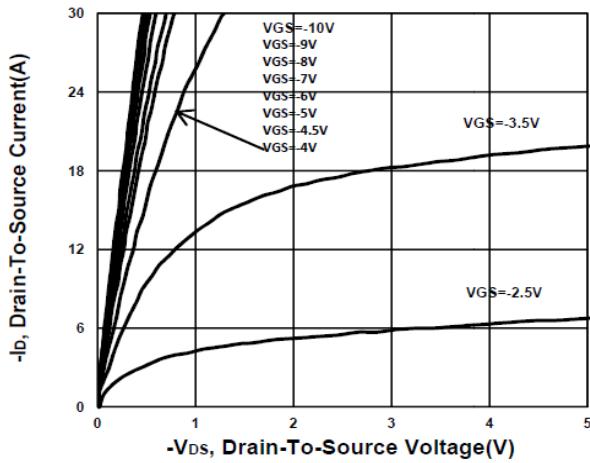
²Independent of operating temperature.

³Package limitation current is 30A.

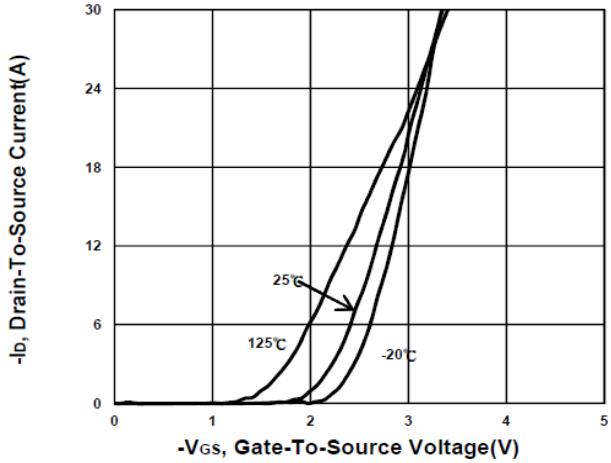
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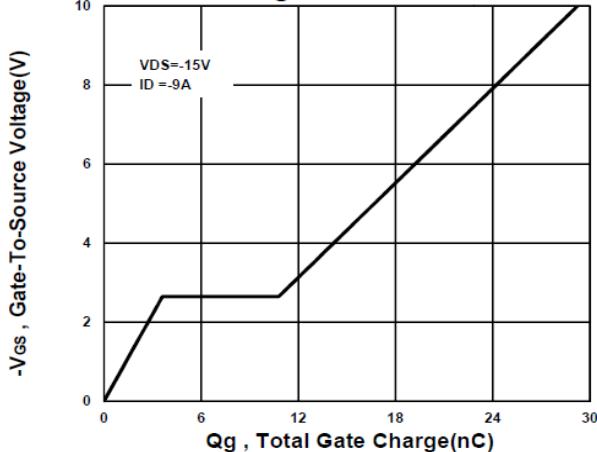
Output Characteristics



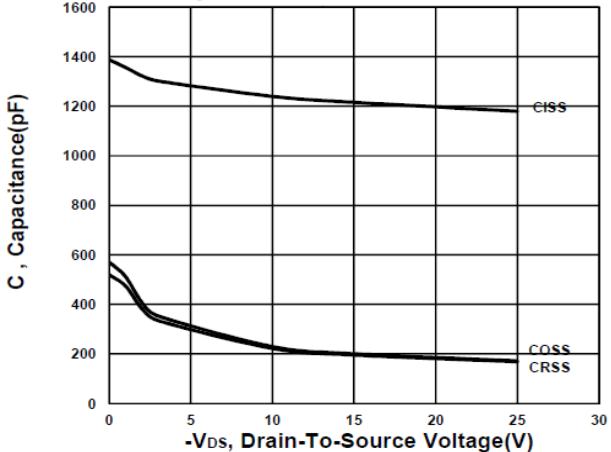
Transfer Characteristics



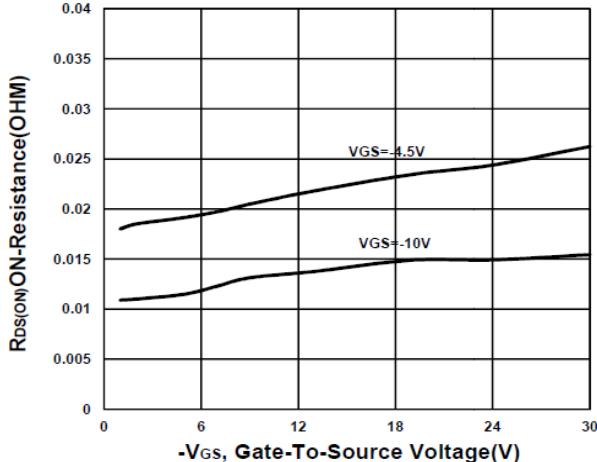
Gate charge Characteristics



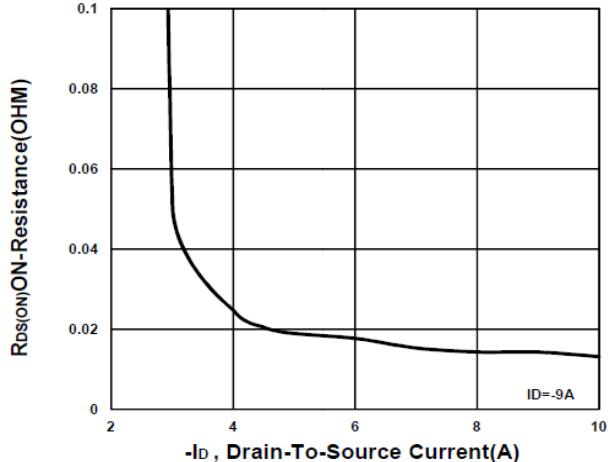
Capacitance Characteristic



On-Resistance VS Gate-To-Source

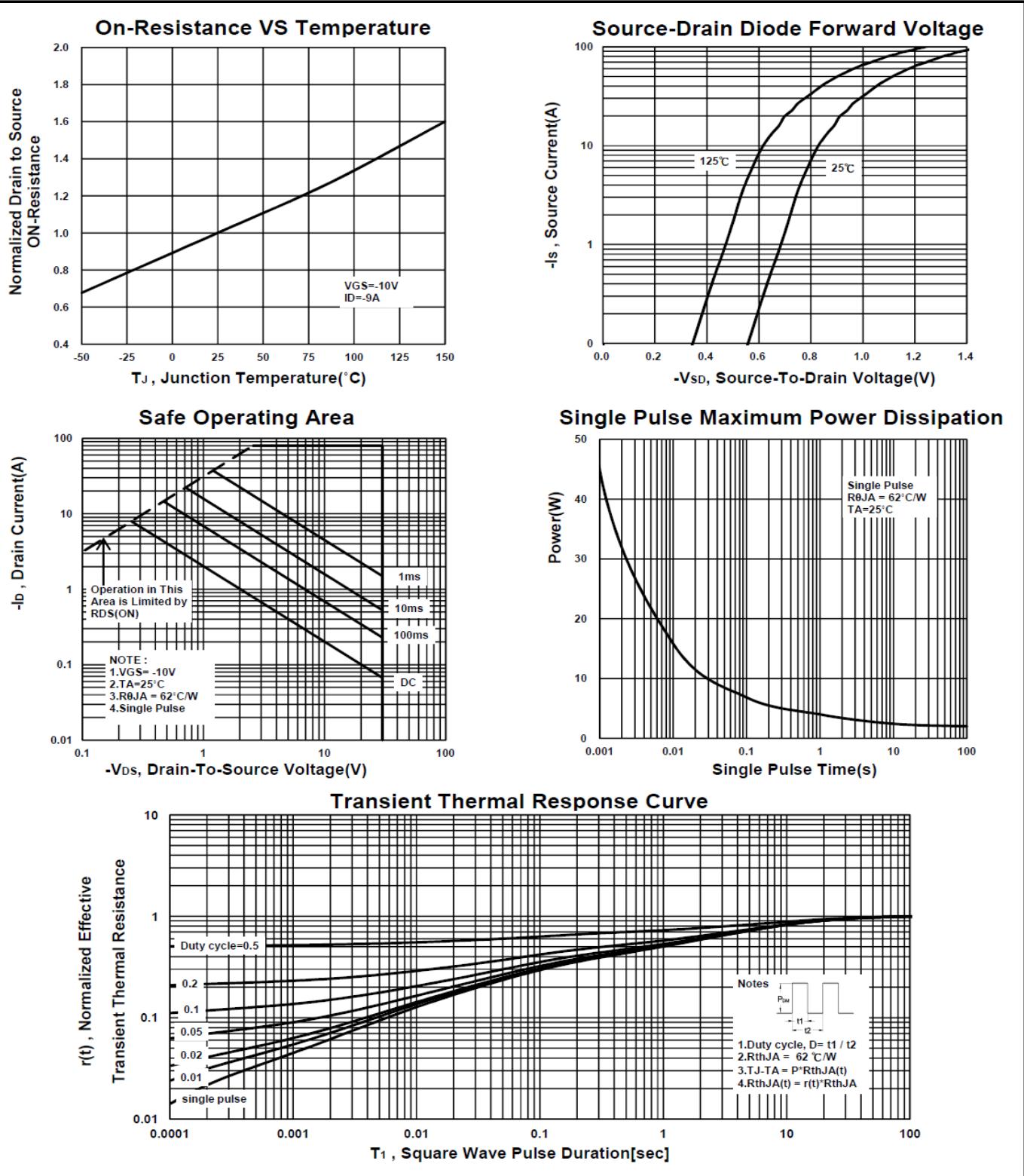


On-Resistance VS Drain Current



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Package Dimension

PDFN 3x3P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	3		3.6	I	0.7		1.12
B	2.88		3.2	J	0.1		0.33
C	2.9		3.2	K	0.6		
D	1.98		2.69	L	0°	10°	12°
E	3		3.6	M	0.14		0.41
F	0		0.455	N	0.6		0.7
G	1.47		2.2	O	0.12		0.36
H	0.15		0.56	P	0		0.2

